FIB Materials and Processes for High Aspect Ratio Circuit Edit

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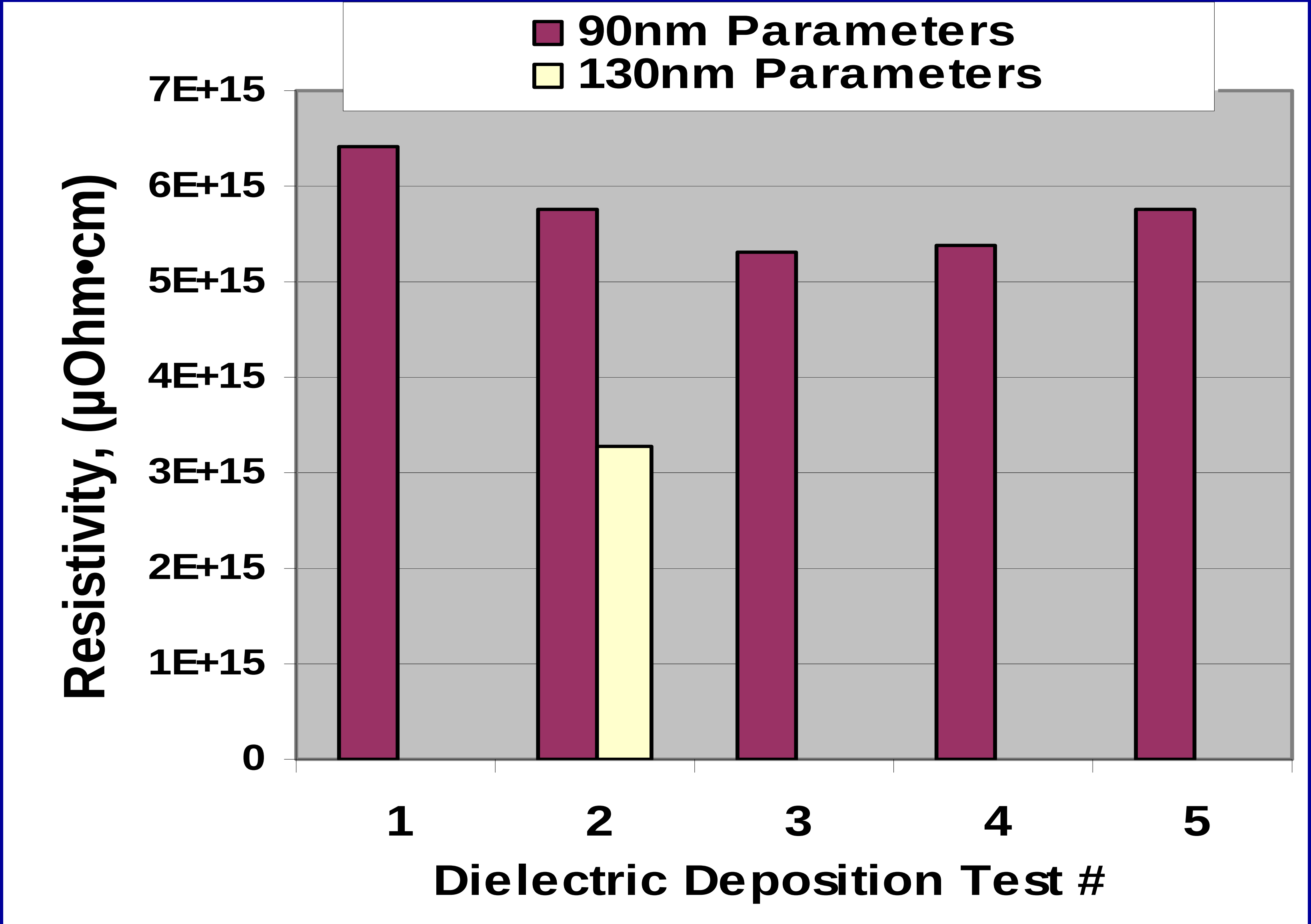
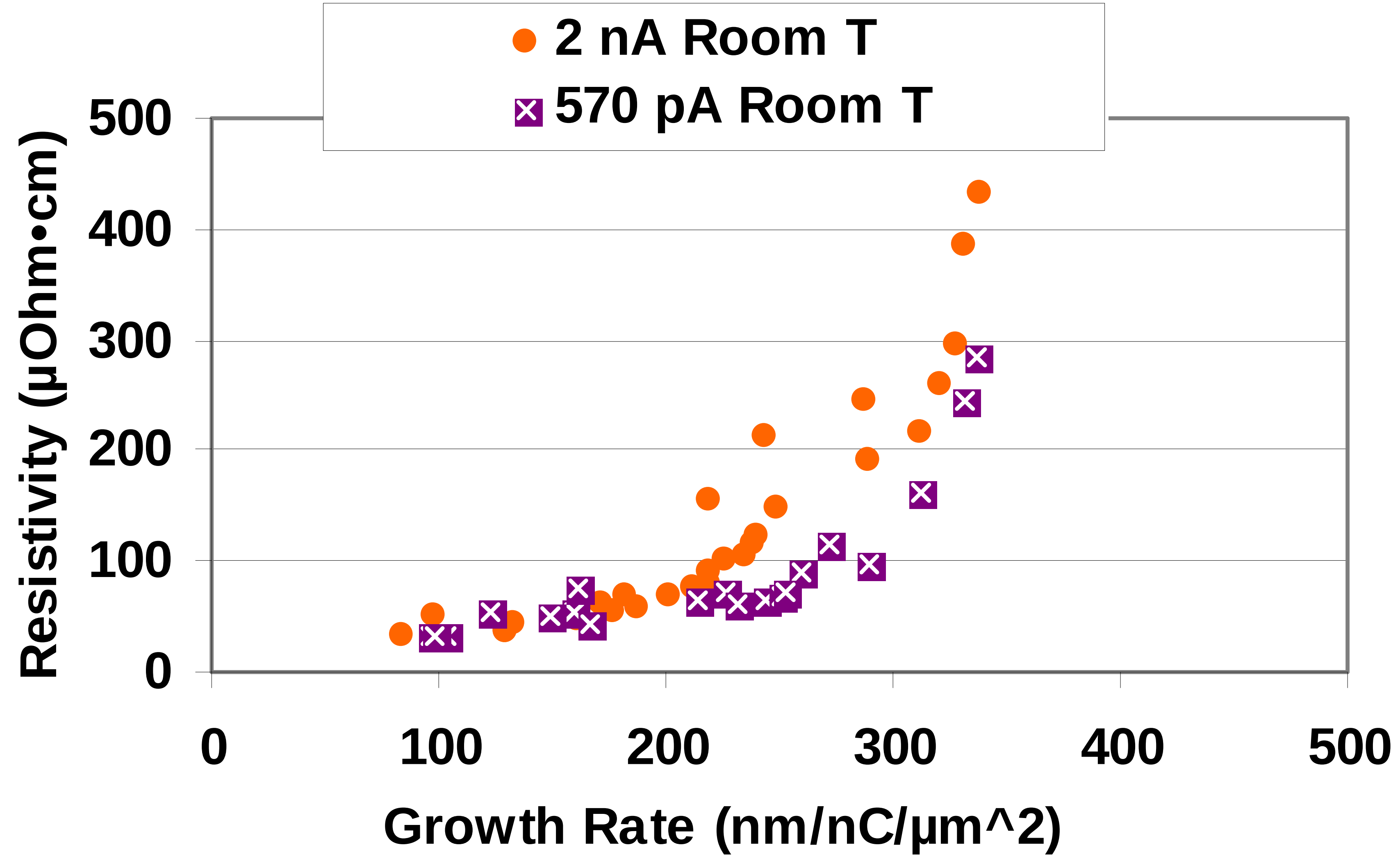
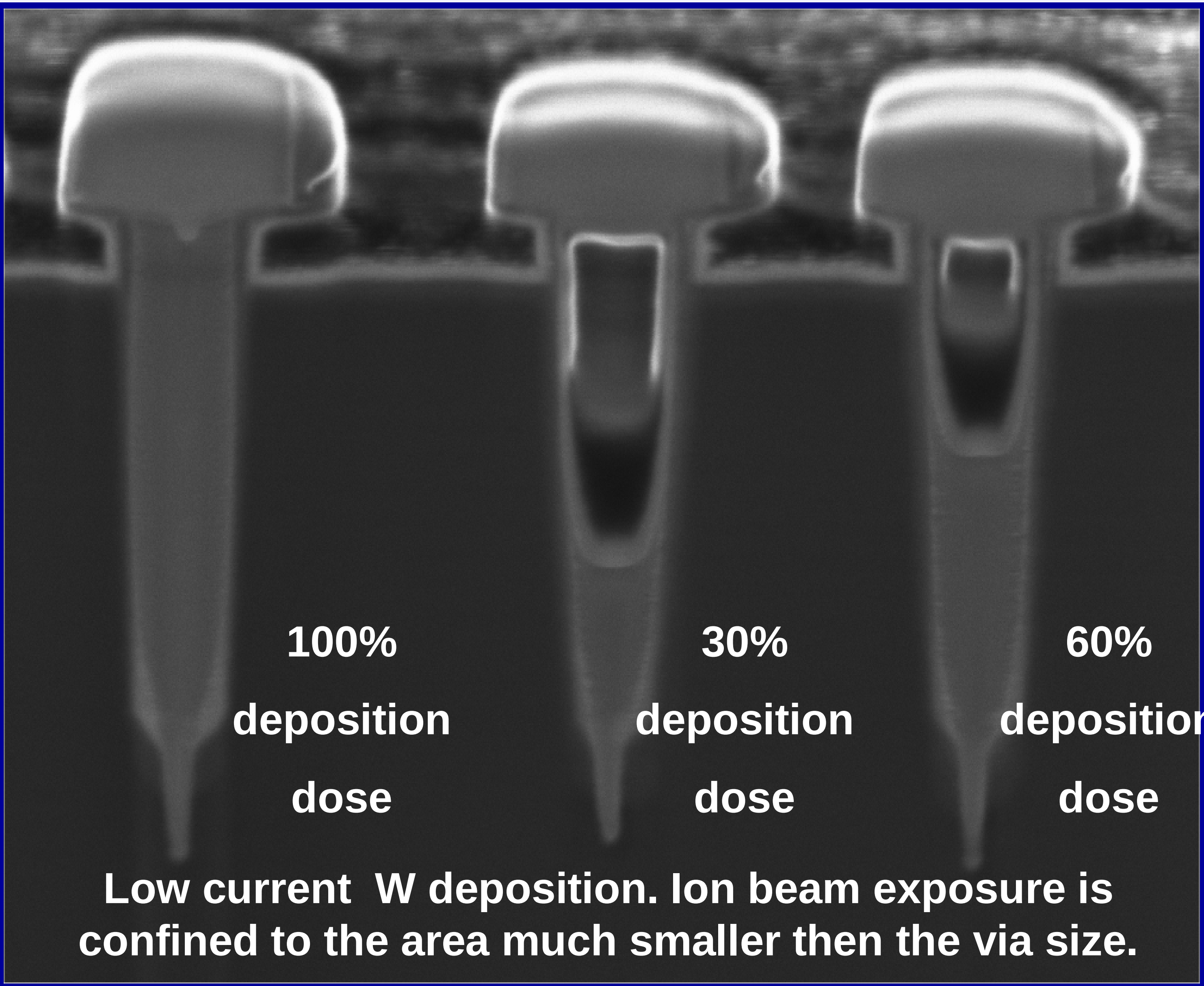
Improved Dielectric Deposition



Copper Deposition on Surface



Void-free HAR Via Filling Process



Low current W deposition. Ion beam exposure is confined to the area much smaller then the via size.